

CHO-BOND® 1029

TWO COMPONENT FLEXIBLE ELECTRICALLY CONDUCTIVE SILICONE ADHESIVE

Customer Value Proposition:

CHO-BOND 1029 is a silver plated copper filled, two-component conductive silicone designed for applications where a flexible, strong, conductive electrical bond must be achieved. CHO-BOND 1029 greatly simplifies the problem of bonding conductive silicone EMI gaskets to metal substrates. It is formulated for relatively small bond lines (less than 0.010 inches [0.25mm]), and should not be used as an EMI caulk where bond lines are greater than 0.10 inches [0.25 mm]. Low volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1029 a good choice for a variety of commercial and military applications. Curing of CHO-BOND 1029 can be achieved in as little as 30 minutes with heat to minimize equipment downtime and increase manufacturing throughput. CHO-BOND 1029 is supplied as a two component system, one part liquid and one part wet powder solid. For optimum mixing and material performance, the sand-like solid part should be added incrementally to the liquid part and mixed slowly over a 10 minute time period.

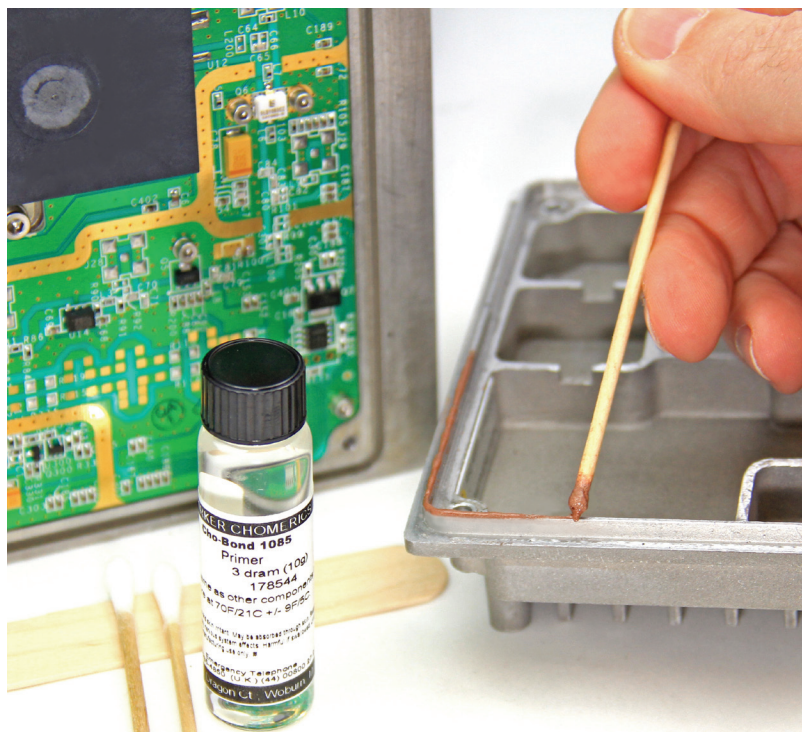
For best adhesion results, CHO-BOND 1029 should be used in conjunction with CHO-SHIELD 1085 primer. Typical applications include bonding, repair, and attachment of EMI gaskets, and sealing around EMI vents and windows.

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Features and Benefits:

- Two component
- Silver plated copper filler
- Low VOCs
- Heat cure silicone
- Non corrosive cure mechanism
- Thick paste
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Good conductivity 0.060 ohm-cm.
- Minimal shrinkage.
- Flexible, 120 minute working life, > 450 psi lap shear strength, 24 hr handling time at room temperature, wide range of application temperatures. 1 week for full cure.
- No corrosive by-products generated during curing to damage substrate.
- Can be used on overhead or vertical surfaces.

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CHO-BOND 1029 - Product Information

Table 1 Typical Properties

CHO-BOND 1029		
Typical Properties	Typical Values	Test Method
Polymer	Silicone	N/A
Filler	Silver-Plated Copper	N/A
Mix Ratio, A : B (by weight)	1.0 : 2.5	N/A
Color	Brownish Red	N/A (Q)
Consistency	Thick Paste	N/A (Q)
Maximum DC Volume Resistivity	0.060 ohm-cm	CHO-95-40-5555* (Q/C)
Minimum Lap Shear Strength**	450 psi (3103 kPa)	CHO-95-40-5300* (Q/C)
Minimum Peel Strength**	6.0 lb./inch (700 N/m)	CHO-95-40-5302* (Q/C)
Specific Gravity	3.1	ASTM D792 (Q/C)
Hardness	80 Shore A	ASTM-D2240 (Q/C)
Continuous Use Temperature	- 55°C to 125°C (-67 °F to 257 °F)	N/A (Q)
Elevated Temperature Cure Cycle	0.5 hour @ 121 °C (250 °F)	N/A
Room Temperature Cure	1 week***	N/A (Q)
Working Life	2.0 hours	N/A (Q)
Shelf Life, unopened	6 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	N/A	N/A
Maximum thickness recommended	0.008 in (0.20 mm)	N/A
Volatile Organic Content (VOC)	14 g/l	Calculated
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	900 in ² (5806 cm ²)	N/A
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	60 feet (18.3 m)	N/A

Note: N/A – Not Applicable, (Q/C) – Qualification and Conformance Test, (Q) – Qualification Test

* This test Method is available from Parker Chomerics.

** Minimum values listed are based on using the CHO-SHIELD 1085 primer that typically comes bundled with the CHO-BOND.

*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

Ordering Procedure

CHO-BOND 1029 is available in 3 oz. (85 g) and 1 lb. (454 g) kits. Each kit includes resin, hardener, primer and instructions.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1029	85	Part A in an 4 oz. and Part B in a 4 oz. polypropylene kit	50-00-1029-0000	1085
	454	Part A in an 8 oz. and Part B in a 6 oz. polypropylene kit	50-01-1029-0000	1085

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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